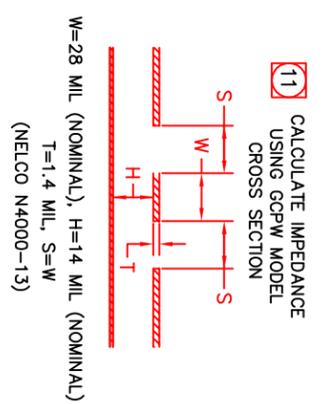
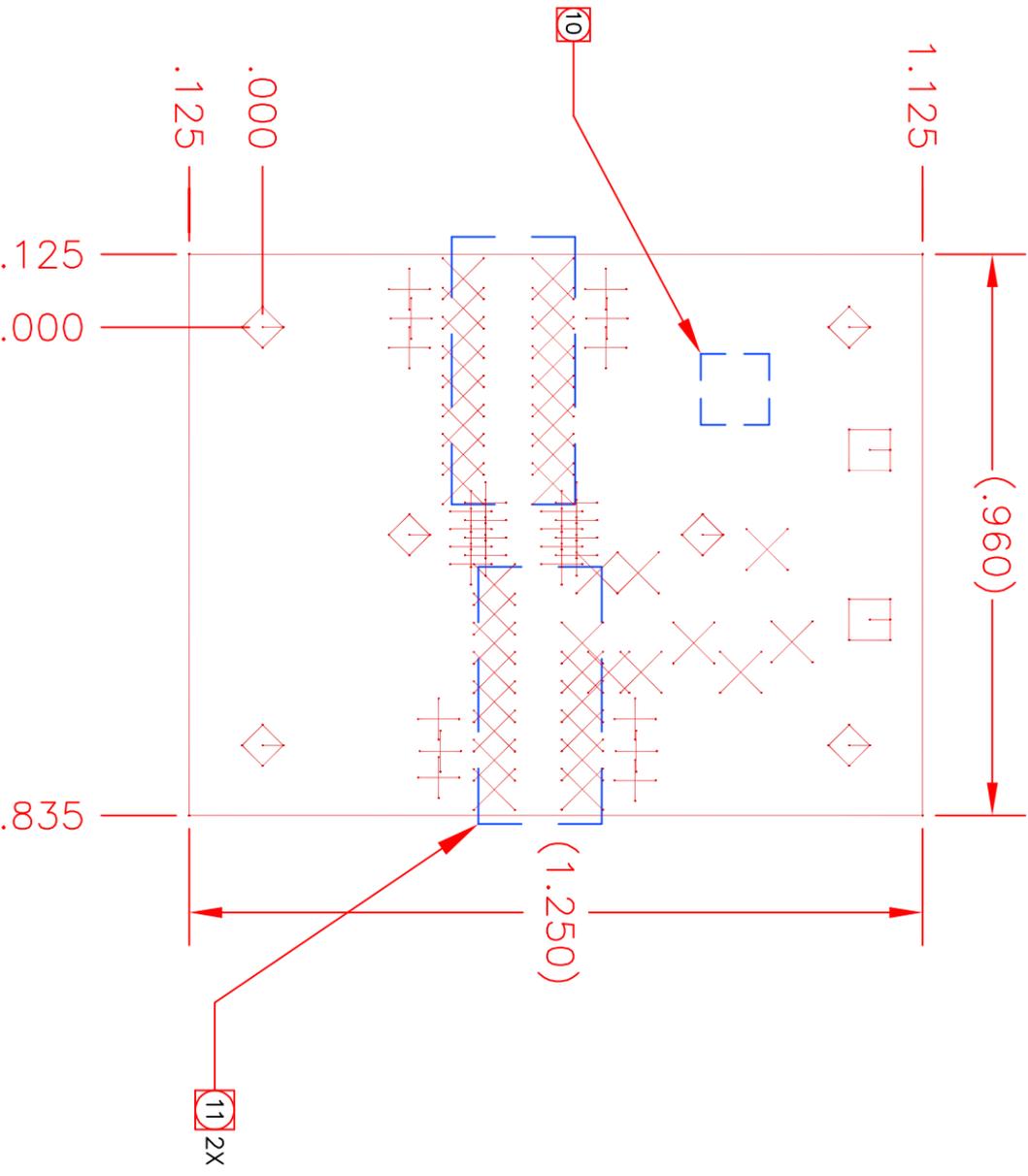
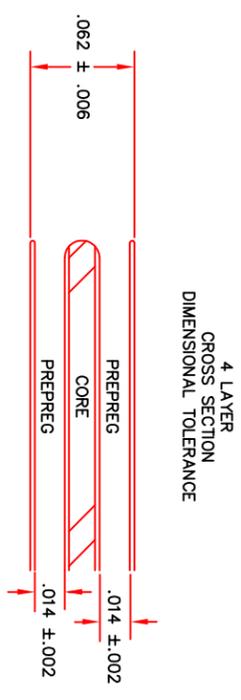
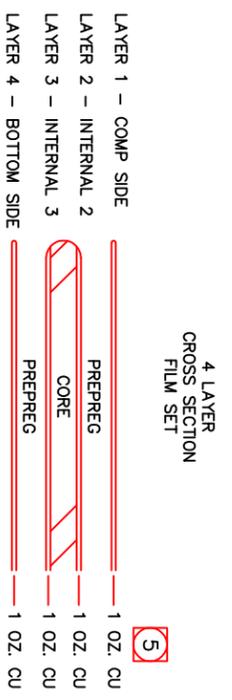


REV	DESCRIPTION	DCN	DATE	BY/APPD

### COMPONENT SIDE

NOTES UNLESS OTHERWISE SPECIFIED:

1. FABRICATE IAW IPC-6012, CLASS 2, CURRENT REVISION.
2. BOARD SHALL MEET THE INSPECTION CRITERIA OF IPC-A-600 CLASS 2, CURRENT REVISION.
3. USE ARTWORK 1082269AW CURRENT REV.
- 4 MATERIAL: NELCO N4000-13, RoHS COMPLIANT.
- 5 FINISHED WEIGHT PER SQUARE FOOT NOMINAL: OUTER LAYERS SHALL BE 1 OZ. INNER LAYERS SHALL BE 1 OZ.
6. DESWEAR HOLES AND VIAS.
- 7 FINISH: ELECTROLESS NI IMMERSION AU (ENIG). GOLD PLATING THICKNESS TO BE BETWEEN 3 - 8 MICRONS.
8. SILKSCREEN TOP SIDE ONLY WITH NONCONDUCTIVE EPOXY INK. COLOR SHALL BE A CONTRASTING INK WITH RESPECT TO SOLDERMASK COLOR. DISTORTION OF SILKSCREEN IS ACCEPTABLE OVER TRACES. REMOVE EPOXY INK FROM SOLDER LANDS.
9. APPLY SOLDERMASK OVER BARE COPPER (SMOBC) IAW IPC-SM-840, TOP SIDE ONLY, USING LPI, COLOR CLEAR OR GREEN. SOLDERMASK OVER VIAS IS NOT ACCEPTABLE.
- 10 SUPPLIER LOT NUMBER/DATE CODE (NO LOGO) SHALL ONLY BE SILKSCREENED WITH NON-CONDUCTIVE EPOXY INK IN APPROX. LOCATION SHOWN.
- 11 CALCULATE IMPEDANCE USING GCPW MODEL. ADJUST RF TRACE WIDTH TO MEET 50 OHMS +/- 5%.
12. INCLUDE A 50 OHM TEST COUPON.



HOLE SCHEDULE (ALL PLATED THRU DIAMETERS ARE AFTER PLATING)

SYM	DESCRIPTION	PLATED THRU	QTY
+	∅.010 +.003/- .010 THRU	YES	28
X	∅.020 ±.003 THRU	YES	38
□	∅.055 ±.003 THRU	YES	2
◇	∅.102 ±.003 THRU	YES	6

THOUGHT SEMICONDUCTOR PROPRIETARY INFORMATION

QTY/ PER DASH NO	ITEM NO	PART OR IDENT NO	CAGE CODE	NOMENCLATURE OR DESCRIPTION	SPEC/STD

UNLESS OTHERWISE SPECIFIED, DIMENSIONS ARE IN INCHES.  
 1X DEC ± .02 THRU .125 INK  
 100X DEC ± .005  
 ANGLES ± 0° 30'

PARTS LIST OR MATERIAL

MATERIAL:	DR: T. Patterson	6-6-11
4	CHK: C. Blum	6-6-11
7		

FINAL PROTECTIVE FINISH:


PCB, EVAL BOARD  
SOT 363

SIZE	CAGE CODE	REV
D	14482	1082269PC
SCALE	W/O NO.	

SHEET 1 OF 1